



MJ N-Channel Super Trench II Power MOSFET

Description

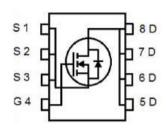
The series of devices uses Super Trench II technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

General Features

- ♦ V_{DS} =100V, I_{D} =75A $R_{DS(ON)}$ =7.4mΩ, typical @ V_{GS} =10V
- ◆ Excellent gate charge x R_{DS(on)} product(FOM)
- ♦ Very low on-resistance R_{DS(on)}
- ◆ 150°C operating temperature
- ◆ Pb-free lead plating

Application

- ◆ DC/DC Converter
- ◆ Ideal for high-frequency switching and synchronous rectification







Schematic Diagram

DFN 5X6

100% UIS TESTED! 100% ΔVds TESTED!

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
P078N10G	MJXP078N10G	DFN5X6-8L	4	-	2

Absolute Maximum Ratings (Tc=25℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	100	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	lo	75	А
Drain Current-Continuous(Tc =100°C)	ID(100°C)	58	А
Pulsed Drain Current	Ідм	300	А
Maximum Power Dissipation	Po	100	W
Derating factor		0.8	W/°C
Single pulse avalanche energy (Note 4)	Eas	387	mJ
Operating Junction and Storage Temperature Range	Тл,Тѕтс	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case	Rejc	1.25	°C/W
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Electrical Characteristics (Tc=25℃ unless otherwise noted)

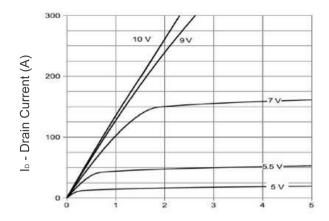
Parameter	Symbol	Condition	Min	Тур	Max	Uni
Off Characteristics						
Drain-Source Breakdown Voltage	BVDSS	V _{GS} =0V I _D =250µA	100	-	-	V
Zero Gate Voltage Drain Current	Ipss	V _{DS} =100V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	Igss	V _{DS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)	<u> </u>					
Gate Threshold Voltage	VGS(th)	V _{DS} =V _{GS} ,I _D =250µA	2.0	3.0	4.0	V
Drain-Source On-State Resistance	RDS(ON)	V _{GS} =10V,I _D =37.5A	-	7.4	8.0	mΩ
Forward Transconductance	g FS	V _{DS} =5V,I _D =37.5A	-	60	-	s
Dynamic Characteristics (Note 3)		ı	1	1		I
Input Capacitance	Ciss		-	3070	-	PF
Output Capacitance	Coss	V _{DS} =50V,V _{GS} =0V F=1.0MHz	-	290	-	PF
Reverse Transfer Capacitance	Crss		_	23	-	PF
Switching Characteristics (Note 3)	'					
Turn-on Delay Time	t _{d(on)}		-	15	-	nS
Turn-on Rise Time	tr	VDD=50V,ID=37.5A	-	10	-	nS
Turn-Off Delay Time	t _{d(off)}	V _{GS} =10V,R _G =1.6Ω	-	34	-	nS
Turn-Off Fall Time	tr		-	8	-	nS
Total Gate Charge	Qg		-	53	-	nC
Gate-Source Charge	Qgs	V _{DS} =50V,I _D =37.5A V _{GS} =10V	_	18	-	nC
Gate-Drain Charge	Q _{gd}		-	16	-	nC
Drain-Source Diode Characteristics	I	<u> </u>	<u> </u>	<u> </u>	<u> </u>	l .
Diode Forward Voltage (Note 2)	VsD	V _{GS} =0V,I _S =37.5A	-	-	1.2	V
Diode Forward Current	Is		-	-	75	А
Reverse Recovery Time	trr	TJ=25°C,IF=37.5A	_	60	-	nS
Reverse Recovery Charge	Qrr	di/dt= 100A/µs (Note 3)	_	106		nC

Notes:

- 1) Repetitive Rating: Pulse width limited by maximum junction temperature.
- ② Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 3 Guaranteed by design, not subject to production
- 4 EAS condition : Tj=25°C,Vbb=50V,Vg=10V,L=0.25mH,Rg=25 Ω

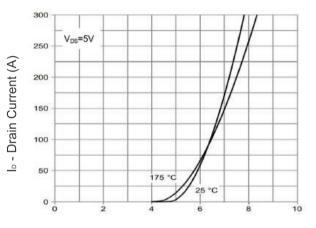


Typical Electrical and Thermal Characteristics



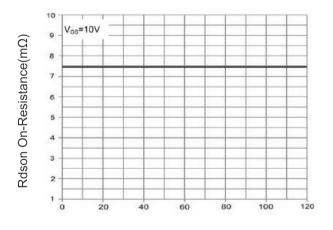
Vds Drain-Source Voltage (V)

Figure 1 Output Characteristics



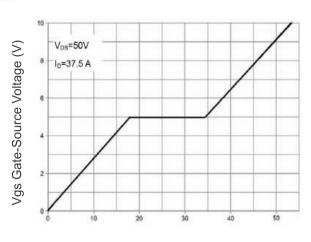
Vgs Gate-Source Voltage (V)

Figure 2 Transfer Characteristics

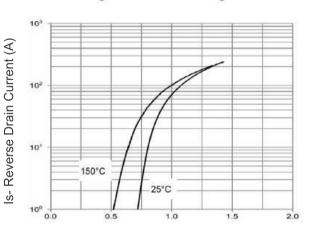


I⊳ - Drain Current (A)

Figure 3 Rdson- Drain Current

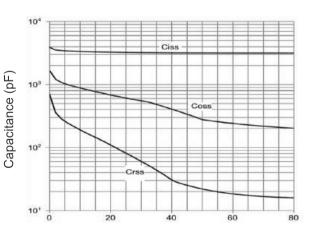


Qg Gate Charge (nC)
Figure 4 Gate Charge



Vsd Source-Drain Voltage (V)

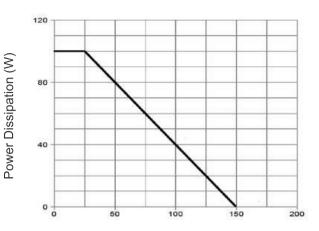
Figure 5 Source- Drain Diode Forward



Vds Drain-Source Voltage (V)

Figure 6 Capacitance vs Vds



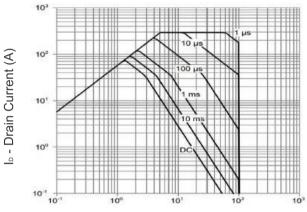


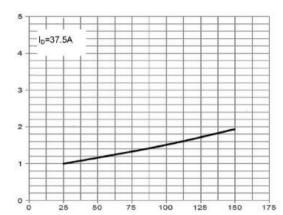
70 Io - Drain Current (A) 100 200

T_J-Junction Temperature(°C)

Figure 7 Power De-rating

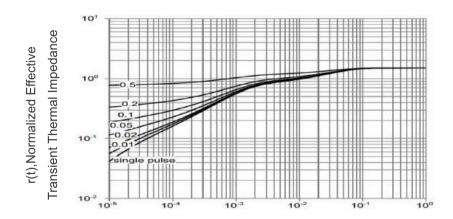
T_J-Junction Temperature(°C) Figure 9 Current De-rating





Vds Drain-Source Voltage (V) Figure 8 Safe Operation Area

 T_J -Junction Temperature(°C) Figure 10 Rdson-Junction Temperature



Normalized On-Resistance

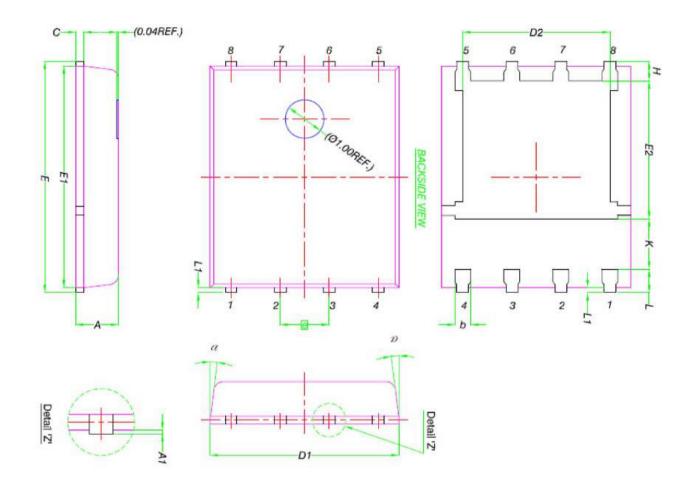
Square Wave Pluse Duration(sec)

Figure 11 Normalized Maximum Transient Thermal Impedance

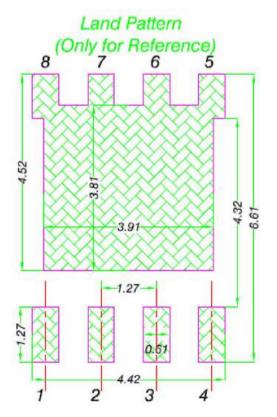




DFN5X6-8L Package Information



DIM.	MILLIMETERS			
	MIN.	NOM.	MAX.	
Α	0.90	1.00	1.10	
A1	0		0.05	
b	0.33	0.41	0.51	
С	0.20	0.25	0.30	
D1	4.80	4.90	5.00	
D2	3.61	3.81	3.96	
Ε	5.90	6.00	6.10	
E1	5.70	5.75	5.80	
E2	3.38	3.58	3.78	
е	1.27 BSC			
Н	0.41	0.51	0.61	
K	1.10	*	*	
L	0.51	0.61	0.71	
L1	0.06	0.13	0.20	
α	O°	-	12°	







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